

Preview

ASM's innovations include the ASM SilverSAM as a powerful sintering solution, the latest generation of the SIPLACE CA for fan-out wafer-level packages, and the SIPLACE TX micron for high-volume system-in-package applications. The AMICRA NANO is a cutting-edge die and flip-chip bonder, specifically engineered for the production of co-packaged optics. Industry-leading precision for ultrathin, conformal films critical to advanced logic, memory, and packaging, enabling angstrom-level control at scale. High-quality crystalline materials innovation has been at the core of everything we do. From deposition to surface modification, we enable the functional layers that define performance, power, and reliability across modern devices. ASM has the expertise and understanding of design & development of System and Sub Systems of: PVD, CVD, RTP, Etch, CMP and related Inspection/ process. Technology leader ASM presents advanced offers a broad selection of packaging solutions for process innovative advanced packaging chains in automotive applications. solutions that can be lined up to complete process chains from wafer pick-up to die fan-out to bonding, molding and packaging. ASM has over 2000+ Person years of experience in serving reputed Semiconductor 'Front-End' and 'Back-End' process equipment manufacturing companies.

Regensburg, Germany, March 12, 2024 - ASMPT AMICRA is excited to announce its participation in OFC 2024,

ASM International N.V. (with ASM standing for Advanced Semiconductor Materials) is a Dutch multinational corporation that designs,

Als größter Lieferant für Best-in-Class Equipment und Partner unterstützt ASMPT Elektronikfertiger beim Aufbau ihrer Intelligent

Automation and digitalization: whether in industry, mobility, healthcare, communications or entertainment - there is hardly any sector

The optical component packaging equipment market was valued at \$4.8 billion in 2025 and is projected to reach \$9.6 billion by 2034,

This technology integrates optical and electronic components into a single housing, offering a high-precision solution for the data

One of our most popular products, the Eagle AERO is the pioneer product to be imbued with the now patented X-Power, thermosonic

ASM optical communication packaging equipment

ASM has the expertise and understanding of design & development of System and Sub Systems of: PVD, CVD, RTP, Etch, CMP

What is Co-Packaged Optics? What is Co-Packaged Optics? Co-Packaged Optics (CPO) is a technology and design approach

Advanced Packaging Advanced packaging means combining dies and SMT components into system-in-package (SiP) applications,

Equipment readiness is key bottleneck for the adoption of panel level packaging & manufacturing. We now see various equipment

ASM delivers a focused set of core technologies that enable atomic level materials control in high volume manufacturing. Industry

From deposition to surface modification, we enable the functional layers that define performance, power, and reliability across

ASM Pacific Technology Ltd (ASMPT), the world's largest supplier of wafer assembly and packaging equipment for the

We believe in ensuring that you enjoy the most reliable and productive wafer processing equipment in the industry. Learn about our

By utilizing advanced packaging techniques, CPO minimizes electrical interconnect lengths and enhances performance, making it

Web: <https://www.morwarreconst.co.za>

